

AMENDMENTS TO THE SPECIFICATION:

Please replace paragraph [0026] with the following amended paragraph:

Referring to FIGS. 4A, and 4B, the housing 110 includes an annular projection 111 in a lower part for holding the supplemental housing 120, and an elastic member 112 inside thereof for elastic supporting of the supplementary housing (telescoping housing) 120.

Please replace paragraph [0027] with the following amended paragraph:

The supplementary housing 120 includes a pusher 126 in an upper part seated on, and held by the annular projection 111 formed inside of the housing 120, and a vacuum tube (a first internal vacuum conduit) 122 inside of the pusher 126.

Please replace paragraph [0029] with the following amended paragraph:

The vacuum tube 122 can be brought into contact with, or move away from, the heat sink 135 containing a second internal vacuum conduit in a central part of the carrier module body 130, and leakage of the vacuum source from a part the vacuum tube 122 is in contact with the heat sink 135 and a first end of the second internal vacuum conduit can be prevented by the O-ring 128 at one end of the vacuum tube 122 so that a vacuum is kept.

Please replace paragraph [0030] with the following amended paragraph:

The heat sink 135 and the second internal vacuum conduit has one end (a second end) in contact with the semiconductor device 101, for receiving temperature variation of the semiconductor device 101. The heat sink 135 can carry out any functions of heat dissipating, or heating.

Please replace paragraph [0046] with the following amended paragraph:

Moreover, a state of holding of the semiconductor device 101, i.e., holding, or the presence of the semiconductor device 101 or not, can be known from the vacuum at the vacuum hole 124.